

What Is Claimed Is:

1. An adhesive composition, comprising:

an insulating resin;

a photopolymerization initiator; and

an oxetan compound.

2. The adhesive composition according to Claim 1,
comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive
composition.

3. The anisotropic conductive adhesive composition
according to Claim 1 or Claim 2, further comprising
electrically conductive particles.

4. A connected structure, wherein electrodes on a
plastic substrate and on a circuit board that are facing each
other are connected by the adhesive composition according to
any of Claims 1 to 3.